

Part Code - CU150



Specification Material: OFHC Copper

Oxygen free high conductivity (OFHC) copper is a suitable sealing material for bakeable UHV systems because of its good conformity with the thermal expansion coefficient of stainless steel as well as its essentially lower hardness (approx. 85 Brinell).

| For Flange OD | D1 | D2 | Pack size |
|---------------|------------|------------|-----------|
| 203 (8.00) | 171 (6.73) | 152 (5.98) | 5 |

